

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL		UNITS
Drain-source Volt.(1)	VDSS	1000	Vdc
Drain-Gate Voltage (R _{GS} =1.0M Ω) (1)	VDGR	1000	Vdc
Gate-Source Voltage Continuous	VGS	± 20	Vdc
Drain Current Continuous (T _c = 25°C)	ID	10	Adc
Drain Current Pulsed(3)	IDM	40	A
Total Power Dissipation	PD	300	W
Power Dissipation Derating > 25°C		2.4	W/°C
Operating & Storage Temp.	TJ/Tsig	-55 TO +150	°C
Thermal Resistance	R _{thJc}	0.42	°C/W
Max. Lead temperature	TL	300	°C

ELECTRICAL CHARACTERISTICS T_c = 25°C (UNLESS OTHERWISE SPECIFIED)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Drain-source Breakdown Volt.	V(BR)DSS	VGS=0V ID=250 μ A	1000	-	-	V
Gate Threshold Voltage	VGS(TH)	VDS=VGS ID=250 μ A	2.0	-	4.5	V
Gate Source Leakage	IGSS	VGS= ± 20 V	-	-	100	nA
Zero Gate Voltage Drain Current	IDSS	VDS=MAX. RATING VGS=0	-	-	250	μ A
		VDS=0.8 MAX. RATING VGS=0 TJ=125°C	-	-	1000	μ A
Static Drain-Source On-State Resistance(1)	RDS(ON)	VGS=10 V ID=5.0A	-	-	1.2	Ω
Forward Trans-Conductance (2)	g _{fs}	VDS $\geq$ 50 V IDS=5.0A	6.0	-	-	S(V)
Input Capacitance	CISS	VGS=0V VDS=25 V	-	4500	-	pF
Output Capacitance	COSS	f=1.0 MHz	-	550	-	pF
Reverse Transfer Capacitance	CRSS		-	160	-	pF
Turn-On Delay	t _{d(on)}	VDD=500V Zo=50 Ω ID=5.0A	-	-	100	ns
Rise Time	t _r	(MOSFET switching times are essentially independent of operating temp.)	-	-	110	ns
Turn-Off Delay	t _{d(off)}		-	-	220	ns
Fall Time	t _f		-	-	105	ns
Total Gate Charge (Gate-Source Plus Gate-Drain)	Qg	VGS=10V, ID=10A VDS=0.8 MAX. RATING	-	145	-	nC
Gate-Source Charge	Qgs	(Gate charge is essentially independent of the operating temperature)	-	55	-	nC
Gate-Drain ("Miller") Charge	Qgd		-	90	-	nC

SOURCE-DRAIN DIODE RATINGS & CHARACT. T_c = 25°C (UNLESS OTHERWISE SPECIFIED)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Continuous Source Current (Body Diode)	IS	Modified MOSFET symbol showing the integral reverse P-N junction rectifier (See schematic)	-	-	10	A
Pulse Source Current (Body Diode) (1)	ISM		-	-	40	A
Diode Forward Voltage (2)	VSD	IF=10A VGS=0V T _c =+25°C	-	-	1.5	V
Reverse Recovery Time	t _{rr}	T _c =+25°C IF=10A	-	600	-	ns
Reverse Recovery Charge	Q _{rr}	di/dt=100A/ μ S	-	8.5	-	μ C

(1) T_J = 25°C to 150°C.

(2) Pulse test: Pulse Width < 300 μ S, Duty Cycle < 2%.

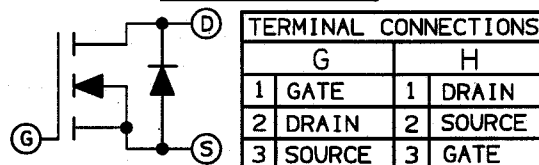
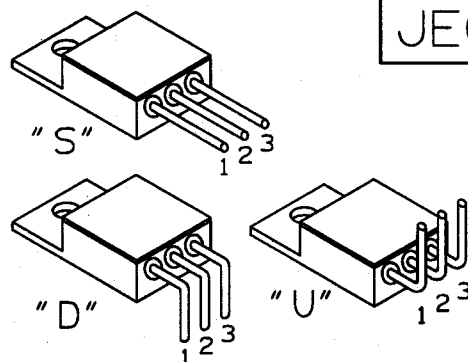
(3) Repetitive Rating: Pulse Width limited By Max. junction Temperature.

1000V, 10A, 1.2 Ω

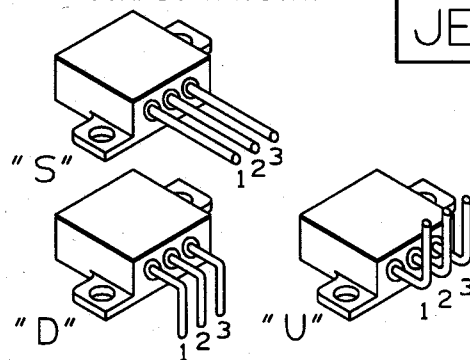
SDF10N100 JEA
SDF10N100 JEB
SDF10N100 JEC
SDF10N100 JED

FEATURES

- RUGGED PACKAGE
- HI-REL CONSTRUCTION
- CERAMIC EYELETS
- LEAD BENDING OPTIONS
- COPPER CORED 52 ALLOY PINS
- LOW IR LOSSES
- LOW THERMAL RESISTANCE
- OPTIONAL MIL-S-19500 SCREENING

SCHEMATIC

STANDARD BEND CONFIGURATIONS


(CUSTOM BEND OPTIONS AVAILABLE)

STANDARD BEND CONFIGURATIONS


(CUSTOM BEND OPTIONS AVAILABLE)

REL. 3/93